



TITLE: SOLDERING AN ELECTRONICS PACKAGE TO A MOTHERBOARD

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SERIAL NO.: 10/808,192 DOCKET NO.: 884.C25US1

REPLACEMENT SHEET

1/3

10

22

COVERING THE PORTION OF ONE OF THE FIRST AND SECOND CONTACTS WITH THE INTERLAYER

- COVERING A PORTION OF BOTH THE FIRST AND SECOND CONTACTS WITH THE INTERLAYER
- COVERING A PORTION OF BOTH THE FIRST AND SECOND CONTACTS WITH THE INTERLAYER
- COVERING ALL EXPOSED PORTIONS OF ONE OF THE FIRST AND SECOND CONTACTS WITH THE INTERLAYER
- ELECTROPLATING THE INTERLAYER ONTO THE PORTION OF ONE OF THE FIRST AND SECOND CONTACTS

15

ENGAGING A FIRST CONTACT ON A MOTHERBOARD WITH A SECOND CONTACT ON AN ELECTRONIC PACKAGE, A PORTION OF ONE OF THE FIRST AND SECOND CONTACTS BEING COVERED WITH AN INTERLAYER THAT HAS LOWER MELTING TEMPERATURE THAN THE FIRST AND SECOND CONTACTS

- PRESSING THE FIRST CONTACT AGAINST THE SECOND CONTACT

20

BONDING THE FIRST CONTACT TO THE SECOND CONTACT BY MELTING THE INTERLAYER TO DIFFUSE THE INTERLAYER INTO THE FIRST AND SECOND CONTACTS, THE BONDED FIRST AND SECOND CONTACTS HAVING A HIGHER MELTING TEMPERATURE THAN THE INTERLAYER BEFORE MELTING

- EXPOSING THE INTERLAYER AND THE FIRST AND SECOND CONTACTS TO AN ENVIRONMENT HAVING A TEMPERATURE GREATER THAN THE MELTING TEMPERATURE OF THE INTERLAYER BUT BELOW THE MELTING TEMPERATURE OF THE FIRST AND SECOND CONTACTS
 - MAINTAINING THE INTERLAYER AND THE FIRST AND SECOND CONTACTS WITHIN THE ENVIRONMENT UNTIL A PORTION OF THE INTERLAYER DIFFUSES INTO THE FIRST AND SECOND CONTACTS
 - MAINTAINING THE INTERLAYER AND THE FIRST AND SECOND CONTACTS WITHIN THE ENVIRONMENT UNTIL A MAJORITY OF THE INTERLAYER DIFFUSES INTO THE FIRST AND SECOND CONTACTS.
 - MAINTAINING THE INTERLAYER AND THE FIRST AND SECOND CONTACTS WITHIN THE ENVIRONMENT UNTIL THE INTERLAYER IS SUBSTANTIALLY DIFFUSED INTO THE FIRST AND SECOND CONTACTS.
- EXPOSING THE INTERLAYER AND THE FIRST AND SECOND CONTACTS TO THE ENVIRONMENT FOR A PERIOD OF TIME
 - EXPOSING THE INTERLAYER AND THE FIRST AND SECOND CONTACTS TO THE ENVIRONMENT UNTIL THE INTERLAYER MELTS AND THEN SOLIDIFIES WITHIN THE FIRST AND SECOND CONTACTS
- EXPOSING THE INTERLAYER AND THE FIRST AND SECOND CONTACTS TO AN ENVIRONMENT HAVING A TEMPERATURE LESS THAN 125 DEGREES CENTIGRADE

Fig. 1

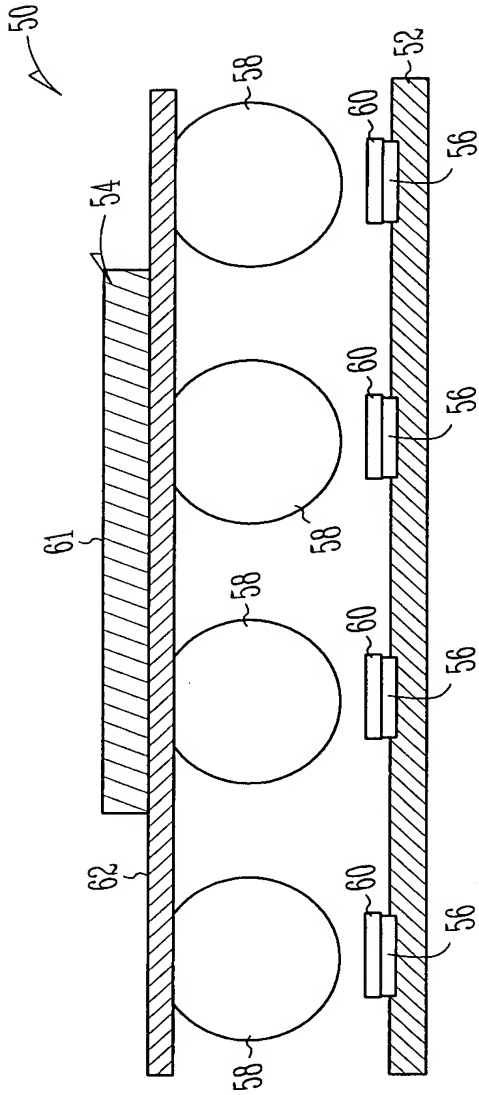


Fig. 2

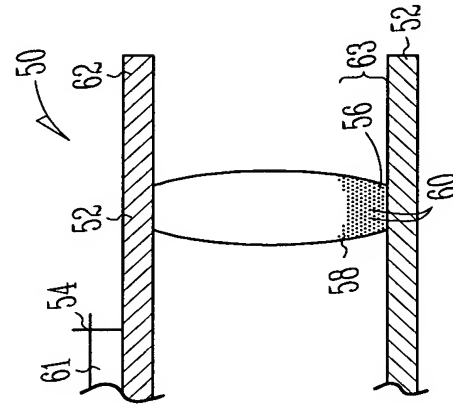


Fig. 4

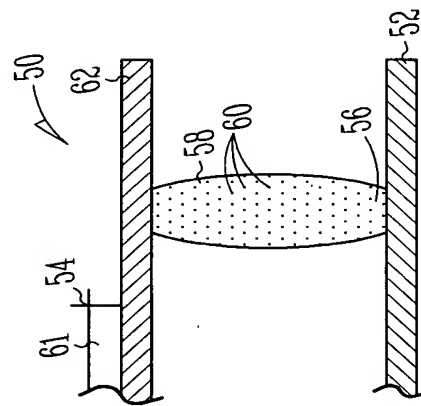


Fig. 3

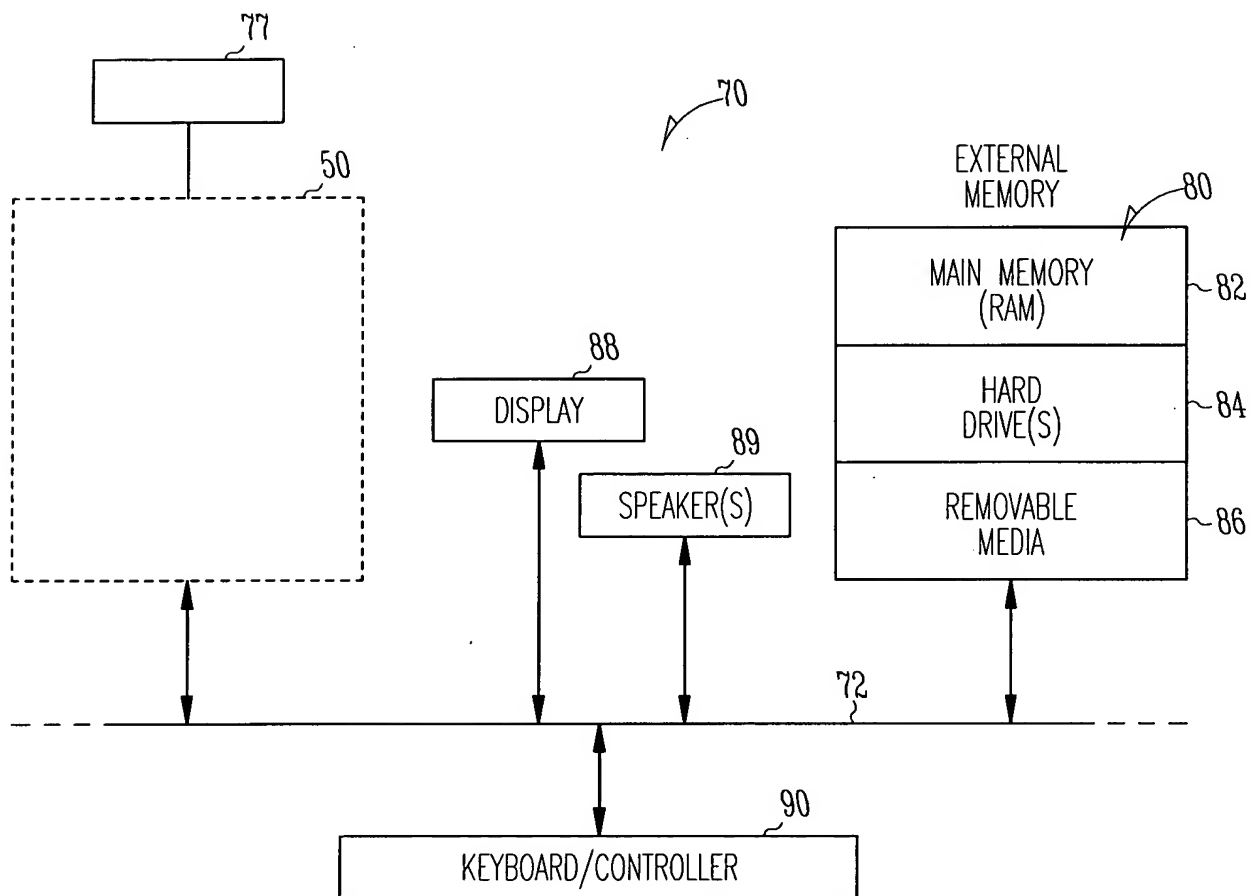


Fig. 5